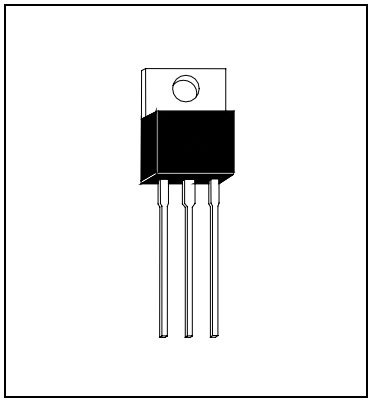
HSB857 / 2SB857

PNP EPITAXIAL PLANAR TRANSISTOR



Description

Low frequency power amplifier.

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
  Storage Temperature ..... -50 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Tc=25°C) ..... 40 W
- Maximum Voltages and Currents
  BVCBO Collector to Base Voltage ..... -70 V
  BVCEO Collector to Emitter Voltage ..... -50 V
  BVEBO Emitter to Base Voltage ..... -5 V
  IC Collector Current ..... -4 A
  IC Collector Current (IC Peak) ..... -8 A

Characteristics (Ta=25°C)

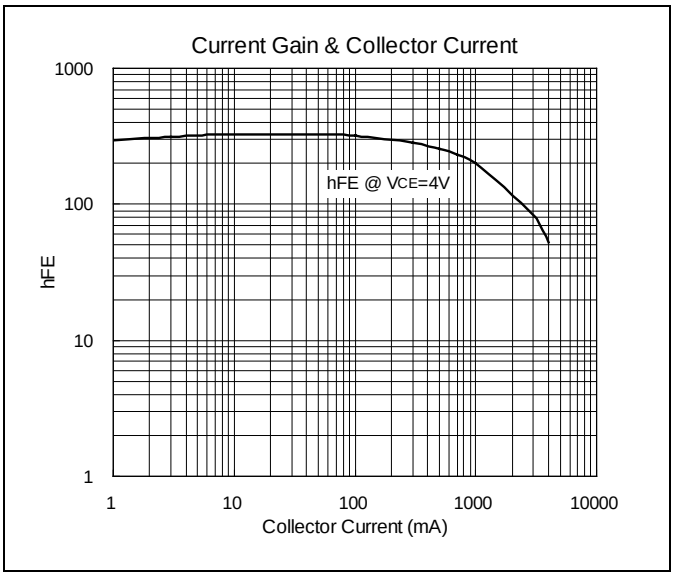
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-70	-	-	V	IC=-10uA, IE=0
BVCEO	-50	-	-	V	IC=-50mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-1	uA	VCB=-50V, IC=0
*VCE(sat)	-	-	-1	V	IC=-2A, IB=-0.2A
*VBE(on)	-	-	-1	V	IC=-1A, VCE=-4V
*hFE1	35	-	-		IC=-0.1A, VCE=-4V
*hFE2	60	-	320		IC=-1A, VCE=-4V
fT	-	15	-	MHz	VCE=-4V, IC=-500mA, f=100MHz

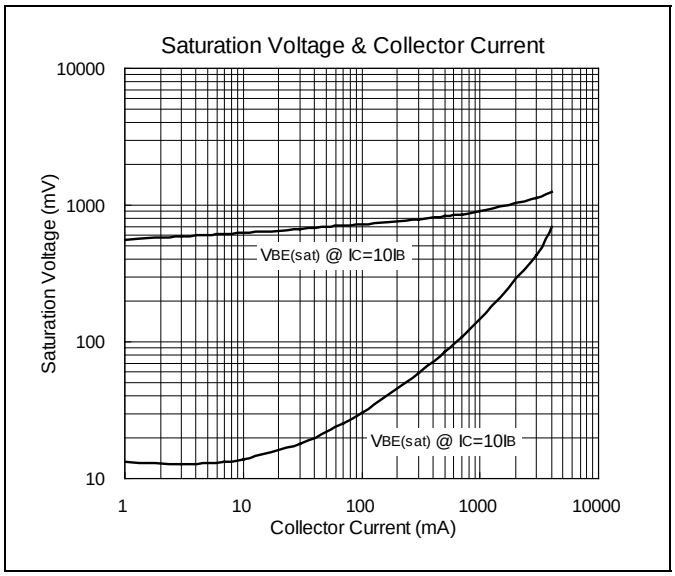
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

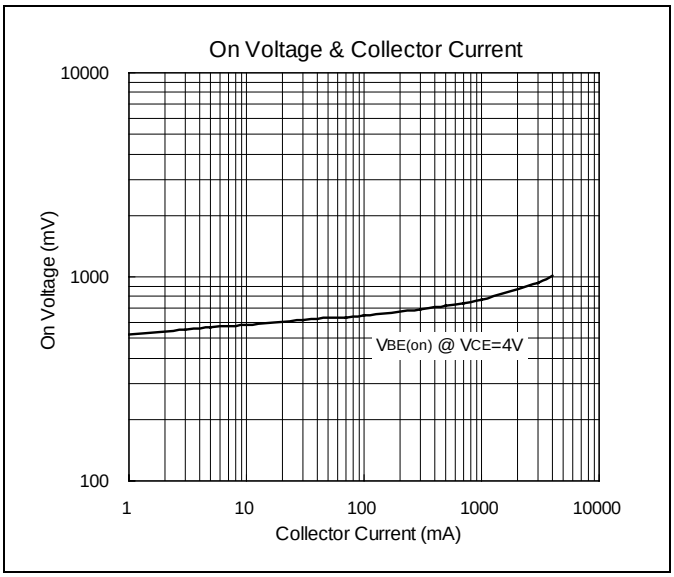
Classification Of hFE2

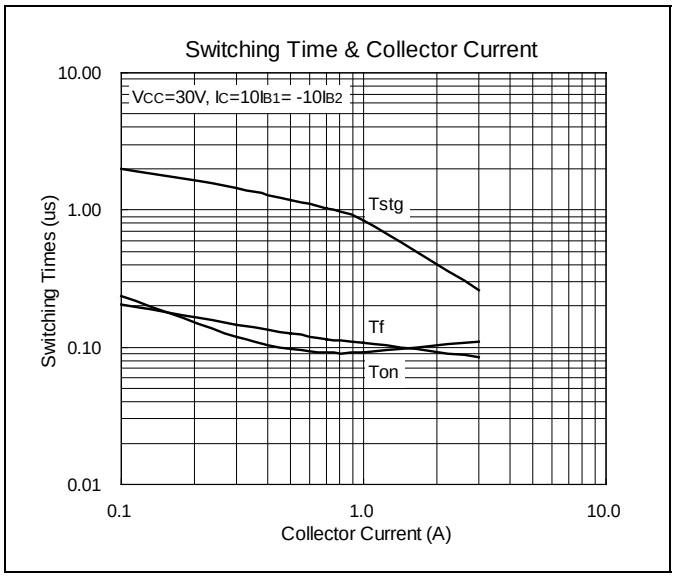
Rank	B	C	D
hFE	60-120	100-200	160-320

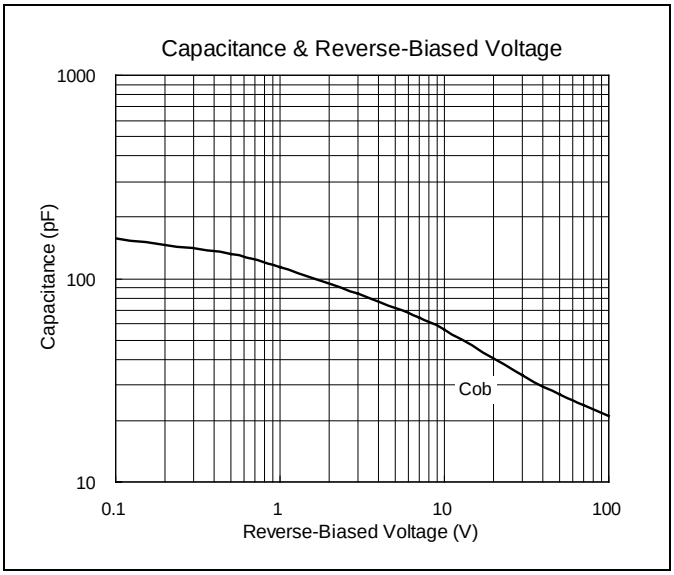
Characteristics Curve

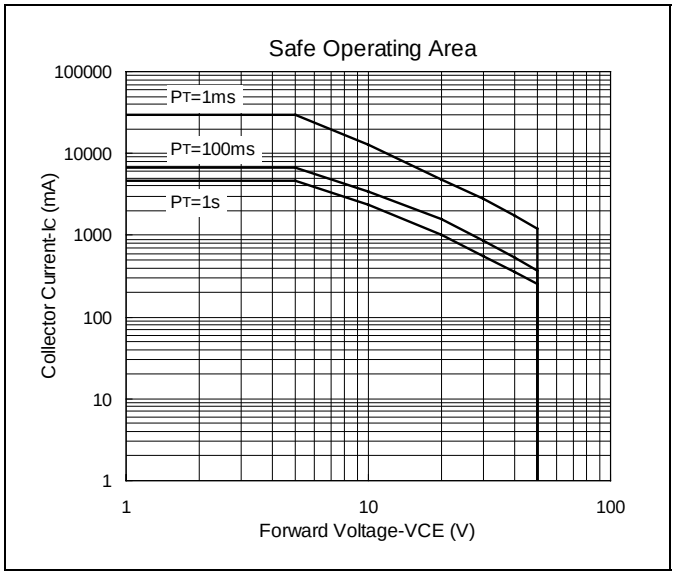




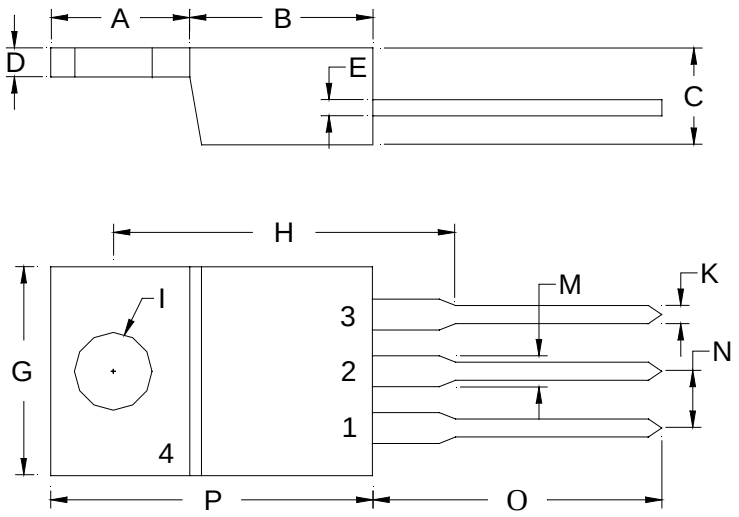




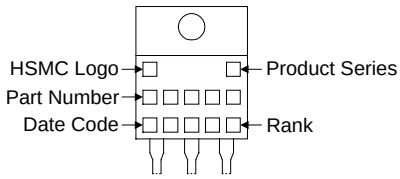




TO-220AB Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-220AB Plastic Package
HSMC Package Code : E

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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